

PHOTOCOUPLER

PS2521-1,-2,-4,PS2521L-1,-2,-4

LARGE FORWARD INPUT TYPE HIGH ISOLATION VOLTAGE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

DESCRIPTION

The PS2521-1, -2, -4 and PS2521L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2521-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2521L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

- Large forward input current (IF = 150 mA)
- High Isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage (VcEo = 80 V)
- High-speed switching ($t_r = 3 \mu s$ TYP., $t_f = 5 \mu s$ TYP.)
- Ordering number of tape product: PS2521L-1-E3, E4, F3, F4, PS2521L-2-E3, E4
- · Safety standards
 - UL approved: File No. E72422 (S)
 - CSA approved: No. CA 101391

APPLICATIONS

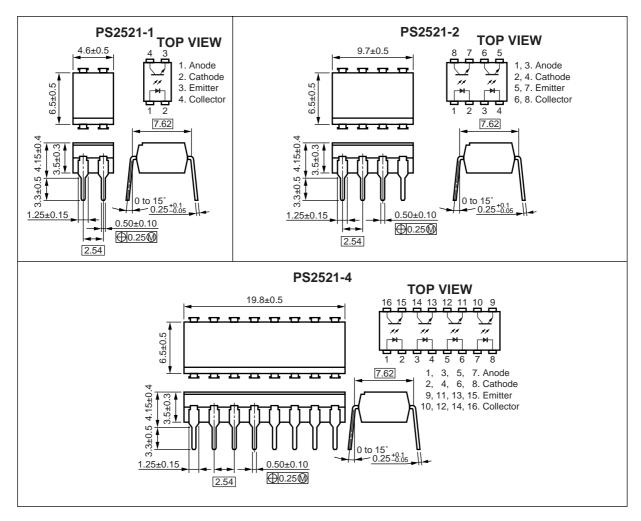
- · Exchange equipment
- FAX/MODEM
- LCR adapter

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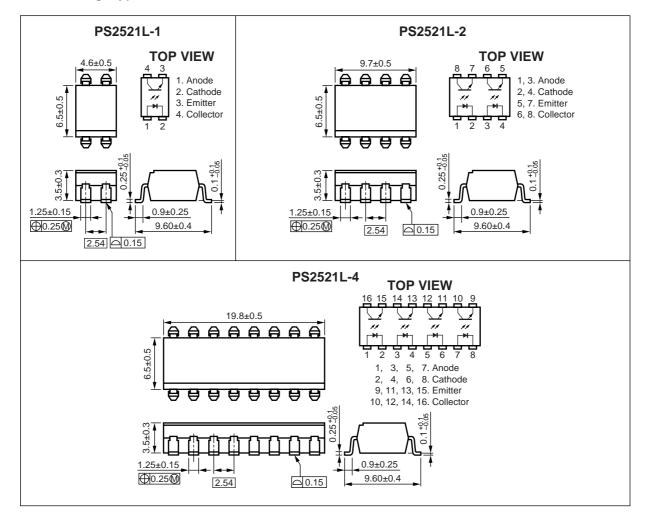
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

★ PACKAGE DIMENSIONS (Unit:mm)

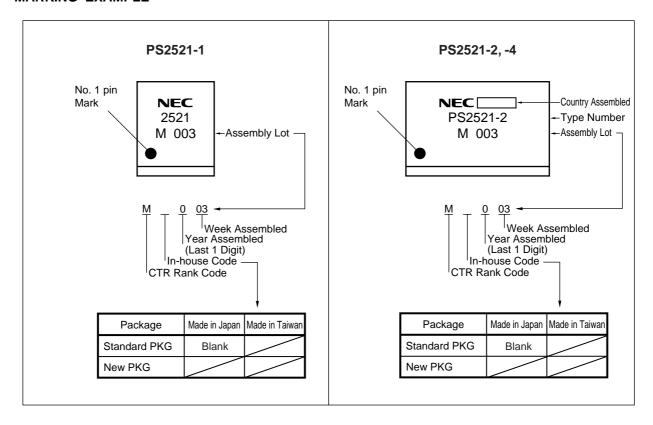
DIP Type



Lead Bending Type



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number*1
PS2521-1	4-pin DIP	Magazine case 100 pcs	PS2521-1
PS2521L-1			
PS2521L-1-E3		Embossed Tape 1 000 pcs/reel	
PS2521L-1-E4			
PS2521L-1-F3		Embossed Tape 2 000 pcs/reel	
PS2521L-1-F4			
PS2521-2	8-pin DIP	Magazine case 45 pcs	PS2521-2
PS2521L-2			
PS2521L-2-E3		Embossed Tape 1 000 pcs/reel	
PS2521L-2-E4			
PS2521-4	16-pin DIP	Magazine case 20 pcs	PS2521-4
PS2521L-4			

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter			Ratings		
		Symbol	PS2521-1, PS2521L-1	PS2521-2, -4, PS2521L-2, -4	Unit
Diode	Forward Current (DC)	İ F	150		mA
	Reverse Voltage	VR	6.0		V
	Power Dissipation Derating	∆Po/°C	2.5	2.0	mW/°C
	Power Dissipation	Po	250	200	mW/ch
	Peak Forward Current 1	I FP	1		Α
Transistor	Collector to Emitter Voltage	Vceo	80		V
	Emitter to Collector Voltage	VECO	6 50		V
	Collector Current	lc			mA/ch
	Power Dissipation Derating	∆Pc/°C	1.5	1.2	mW/°C
	Power Dissipation	Pc	150	120	mW/ch
Isolation Voltage ²		BV	5 000		Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100		°C
Storage Temperature		Tstg	−55 to +150		°C

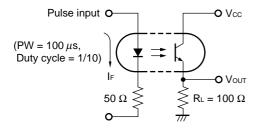
^{*1} PW = 100 μ s, Duty Cycle = 1 %

^{*2} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

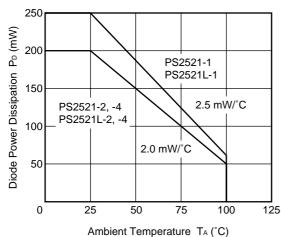
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 100 mA		1.3	1.7	V
	Reverse Current	I R	VR = 5 V			5	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		70		pF
Transistor	Collector to Emitter Dark Current	Iceo	VcE = 80 V, IF = 0 mA			100	nA
Coupled	Current Transfer Ratio (Ic/IF)	CTR	IF = 100 mA, VcE = 3 V	20		80	%
	Collector Saturation Voltage	VCE(sat)	I _F = 100 mA, I _C = 4 mA			0.3	V
	Isolation Resistance	R _{I-O}	VI-0 = 1.0 kVDC	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.6		pF
	Rise Time*1	tr	Vcc = 10 V, Ic = 2 mA, RL = 100 Ω		3		μs
	Fall Time ^{*1}	tf			5		

*1 Test circuit for switching time

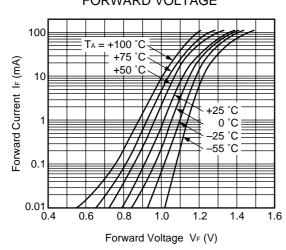


TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

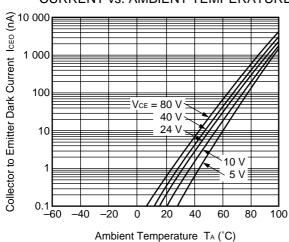




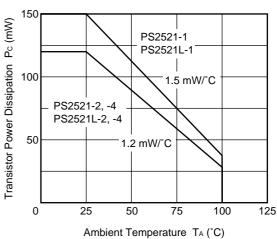
FORWARD CURRENT vs. FORWARD VOLTAGE



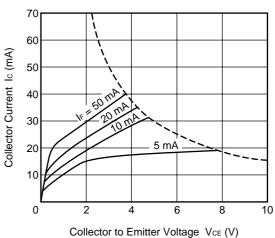
COLLECTOR TO EMITTER DARK **CURRENT vs. AMBIENT TEMPERATURE**



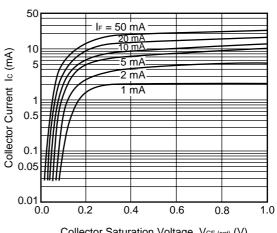
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

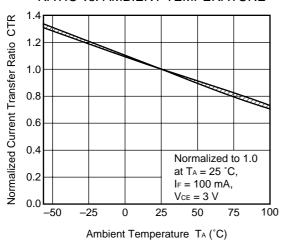


COLLECTOR CURRENT vs. **COLLECTOR SATURATION VOLTAGE**

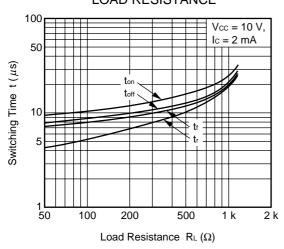


Collector Saturation Voltage VcE (sat) (V)

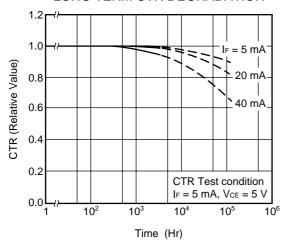
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

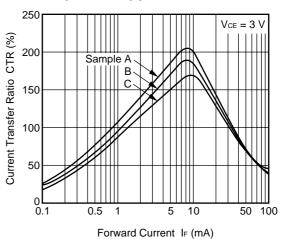


LONG TERM CTR DEGRADATION

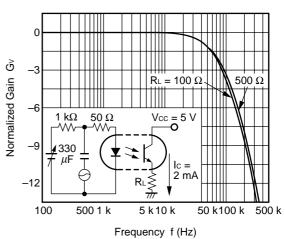


Remark The graphs indicate nominal characteristics.

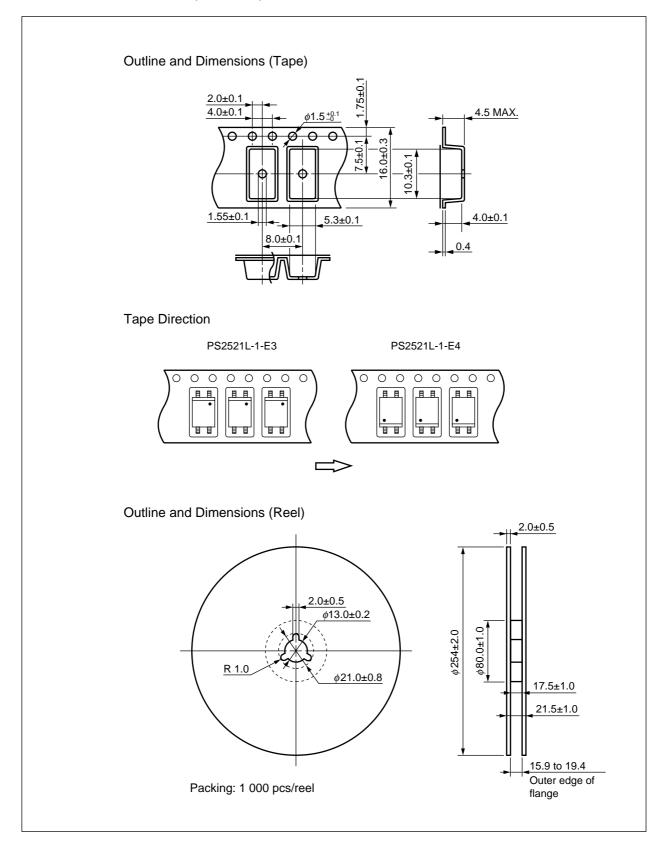
CURRENT TRANSFER RATIO vs. FORWARD CURRENT

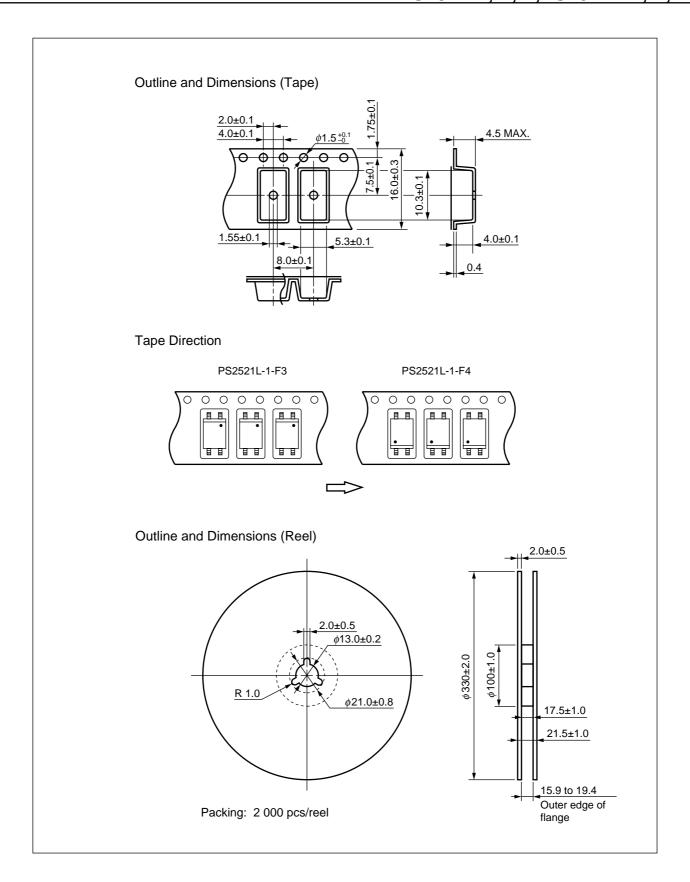


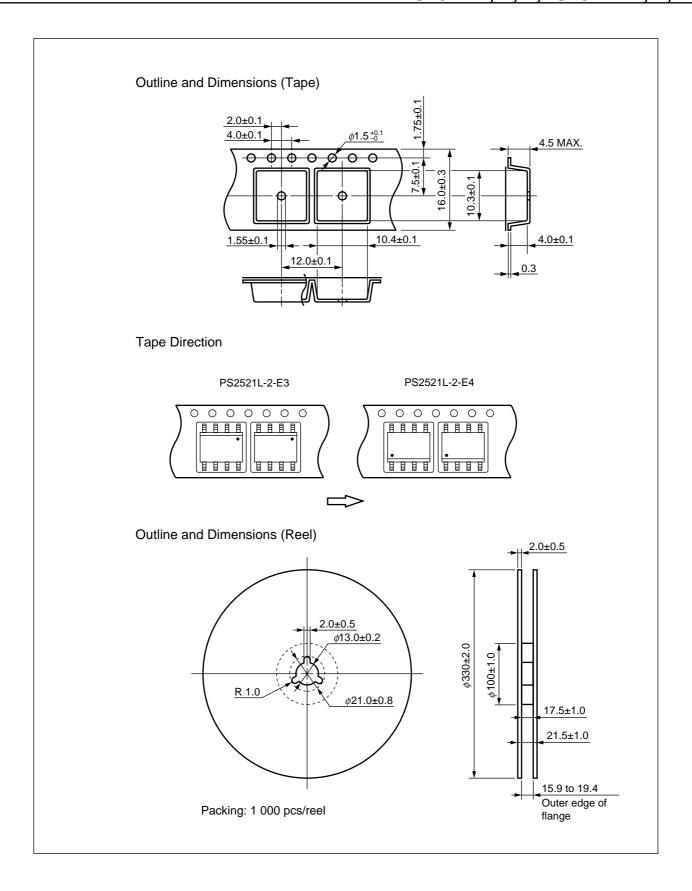
FREQUENCY RESPONSE



★ TAPING SPECIFICATIONS (Unit:mm)







NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

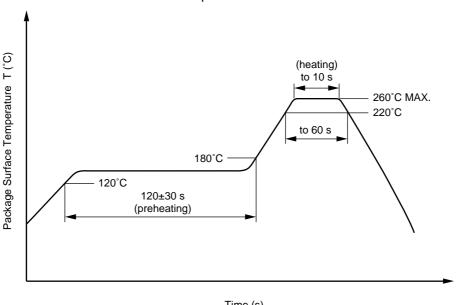
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

· Number of times One (Allowed to be dipped in solder including plastic mold portion.)

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine • Flux

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

★ USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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SAFETY INFORMATION ON THIS PRODUCT

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GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

▶For further information, please contact

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